



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-09-27
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STTH802B-TR	HWDP*D81F01F	A	ASE WEIHAI	2016-09-27
Amount		UoM	Unit type	ST ECOPACK Grade
320.00		mg	Each	ECOPACK2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
SIP	6.5-6.1-2.3	3	GULL WING	
Comment	TO 252 DPAK			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	HWDP*D81F01F					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	2.676	mg	supplier	die	Silicon (Si)	7440-21-3		2.610	mg	975336	8156
				supplier	metallization	Aluminium (Al)	7429-90-5		0.032	mg	11958	100
				supplier	Passivation	Silicon Oxide	7631-86-9		0.011	mg	4111	34
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.001	mg	374	3
				supplier	back side metallization	Gold (Au)	7440-57-5		0.004	mg	1495	13
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.018	mg	6726	56
Leadframe	Copper & its alloys	164.944	mg	supplier	alloy	Copper (Cu)	7440-50-8		164.152	mg	995198	512975
				supplier	alloy	CopperPhosphorous (CuP)	12517-41-8		0.330	mg	2001	1031
				supplier	alloy	Cobalt (Co)	7440-48-4		0.462	mg	2801	1444
Soft solder	Solder	2.623	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high mel	2.505	mg	955013	7828
				supplier	solder	Silver (Ag)	7440-22-4		0.066	mg	25162	206
				supplier	solder	Tin (Sn)	7440-31-5		0.052	mg	19825	163
Bonding wires	Other inorganic materials	0.369	mg	supplier	wire	Aluminium (Al)	7429-90-5		0.369	mg	1000000	1154
Encapsulation	Other Organic Materials	148.343	mg	supplier	mold compound	Silica, vitreous	60676-86-0		133.138	mg	897501	416056
				supplier	mold compound	Epoxy resin	25068-38-6		10.384	mg	70000	32450
				supplier	mold compound	Phenol resin	29690-82-2		4.450	mg	29998	13906
				supplier	mold compound	carbon black	1333-86-4		0.371	mg	2501	1159
Connections coating	Solder	1.045	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.045	mg	1000000	3266